



**TEA PARTNERS WITH PACKAGING SERVICES FIRM  
PACKAGE SCIENCE SERVICES WILL BENEFIT TEA CUSTOMERS**

**Santa Clara, California, January 11, 2011** – Thermal Engineering Associates (TEA) announced today that it is partnering with engineering services firm, Package Science Services (PSS) to provide measurement, modeling and simulation of IC packages for a number of its customers.

“Our mission is to provide best-in-class package engineering services from concept through mass production,” said PSS President, Tom Tarter, “Using our extensive inventory of hardware and software tools and over 25 years experience in microelectronic and optical package engineering, PSS can provide a solution for a broad array of electrical design and performance problems.”

PSS provides high-frequency electrical measurements to 50GHz coupled to a precision probe station with XYZ accuracy to less than 2um. Electrical modeling and simulation services are available using SPICE, IBIS or frequency dependent behavioral models from the chip to the system board. Full-wave electrical modeling for arbitrary structures is available for high-speed digital and RF/EMI problem solving.

The pooling of TEA and PSS resources provides extensive thermal measurement and modeling capability for IC, diode, transistor, LED, and PV devices and related packaging alternatives. These capabilities extend to heat sink and interface materials, cooling channel design, heat movers such as vapor chambers and heat pipes and optimization of thermal management for 3D packaging and stacked chips.

“I am thrilled with this partnership,” said TEA President, Bernie Siegal, “Tom has one of the most complete independent electrical measurement laboratories available. This really differentiates him from most consultants in that he can make the measurements to back up his modeling results.”

**About Thermal Engineering Associates:**

TEA and its president, Bernie Siegal, have been providing thermal test and measurement hardware, software, and consulting services since 1973. Siegal has been chairman of the JEDEC JC15 committee and is the principle author of many MILSTD 750 thermal test methods. All major semiconductor companies, packaging companies, and many system level OEMs have utilized TEA equipment and/or services during its long history. Siegal is a founding member of IEEE SEMI-THERM and has delivered numerous papers and articles on thermal testing, simulation, and evaluation methods and techniques and is frequently sought out as a lecturer and expert in the field.  
<http://www.thermeng.com>

**About Package Science Services:**

PSS provides multidisciplinary electronic package design, modeling, simulation and analysis with expert services from concept to mass manufacturing.

<http://pkgscience.com>

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